Fujitsu MCU Part Numbering Guide

MB 96 F 338 UW A PMC - GS – BND - ER E2

Product Revision
Die Revision: A, B, C, G, H, R, HC
L = Low Power
SL = Super Low Power

Category/Quality grade
G = General-grade 100ppm
ES = Engineering Sample
GS = Automotive grade 50ppm
GT = 10ppm

Product Feature Options
YS = Low voltage reset On/Single clock
RS = Low voltage reset can be On/off, Single clock
YW = Low voltage reset On / Dual clock
RW = Low voltage reset can be On/off / Dual clock
US = USB , Low voltage reset can be On/off , Single clock
UW= USB, Low voltage reset can be On/off , Dual clock

Package Suffix based on dimension/shape
P = Plastic DIP
PF = Plastic SOP/Flat Pack
C = Ceramic DIP
CF = Ceramic QFP
SH = Plastic SDIP
PFM = Plastic QFP/LQFP
PMT = Plastic QFP/LQFP
PFV = Plastic QFP/LQFP
PFS = Plastic QFP
CR = Ceramic PGA
PFF = Plastic LQFP
PMC = Plastic LQFP
PMC1 = Plastic LQFP
PMCR = Plastic LQFP

Lead Form
BND = Bend Lead
STR = Straight Lead
SH = Shrink Pitch

Device Series
Three numbers designate device series with the options of two letter variations.
Possible numbers: 101 to 999 (could be Customer specific and specify memory size)

Memory Type
Blank: Mask ROM
F = Flash ROM
P = OTP ROM
T = External ROM
V = Evaluation device
FV = Flash/Evaluation
M = Multi chip Module
MF=Multi chip Module/Flash
W = EPROM

Number of Bits
89 = 8bit, F^2MC-8L
90 = 16bit F^2MC-16L/LX
91 = 32bit FR
95 = 8bit, F2MC-8FX
96 = 16bit F^2MC-16FX

Tape Specification
ER = Right Facing Tape/Reel
EF = Left Facing Tape/Reel

Fujitsu Microelectronics Semiconductor ID
MB = Micro Block

Environmental Code
E1 = Pb(lead)-free Package
E2 = Pb(lead)-free, Sn (Bismuth) free